Session TH4C

Microwave Packaging and Interconnect Technology

Chairman:

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Highly integrated microwave and millimeter wave components and subsystems are being developed for a broad range of commercial and defense applications. A key aspect of achieving the size, weight and affordability requirements of these products is the development of high density microwave packaging and interconnect technologies. The papers presented in this session address advanced packaging materials; flip-chip mounting of MMICs; analysis and simulation of packages and novel interconnect structures; and advanced package fabrication techniques.

3:30 p.m.–5:00 p.m., Thursday, May 18, 1995
Room 12A,B,C